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Novel Materials and Processes for Electronic Packaging

Guest Editor:

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Deadline for manuscript submissions: closed (10 December 2022)

Message from the Guest Editor

Dear Colleagues,

Driven by new applications ranging from super-computing and fifth/sixth-generation (5G/6G) communications to electric vehicles (EVs) and green energy, advanced highdensity electronic packaging technologies, as well as highpower electronic interconnection are in great demand in the electronic industry. Meanwhile, sustainable materials and manufacturing technologies are also needed to meet the low-emission requirements for carbon neutrality. To achieve high-density and high-reliable electronic devices with low energy consumption, innovative materials and processes for electronic packaging play key roles. For highdensity packaging, three-dimensional (3D) integration is an emerging technology, while for sustainable processes, lowtemperature processes are desired. The 3D structures involve through-silicon-via (TSV), advanced ceramic substrates, and metal-to-metal or metal-to-ceramics bonding, which require various kinds of electronic interconnection technologies.

Research papers and critical reviews on these fields are both highly welcome.

Specialsue



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Message from the Editor-in-Chief

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